AMENDMENTS TO THE CLAIMS

1 (Currently amended). An electrically conductive paste which ~~is~~ can be used for forming wiring conductors and which ~~is~~ can be co-fired ~~in~~ when firing for sintering ceramic layers in a multilayer ceramic substrate provided with the plurality of laminated ceramic layers ~~laminated and~~ with the wiring conductors disposed in association with the ceramic layers, the electrically conductive paste comprising

a metal powder, a glass frit, and an organic vehicle,

wherein an inorganic component [[,]] which is not sintered at a sintering temperature capable of sintering the ceramic layer in the firing [[,]] is disposed on particle surfaces of the metal powder, and

the glass frit has a softening point 150°C to 300°C lower than the sintering temperature.

2 (Currently amended). The electrically conductive paste according to Claim 1, wherein ~~the sintering temperature is 800°C to 1,000°C, and~~ the softening point of the glass frit is 650°C to 850°C.

3 (Currently amended). The electrically conductive paste according to Claim 1, wherein ~~a temperature at which holds for the viscosity of~~ the glass frit ~~is present~~ has a viscosity within the range of 800°C to 950°C. which satisfies $\log(\eta/Pa \cdot s) = 4$.

4 (Original). The electrically conductive paste according to Claim 1, wherein the content of the inorganic component is 0.5 to 8 percent by weight relative to the total weight of the metal powder and the inorgani1c component.

5 (Currently amended). A multilayer ceramic substrate comprising a plurality of laminated ceramic layers ~~laminated~~ and at least one wiring conductor ~~conductors~~ disposed in association with the ceramic layers, wherein the wiring conductor is a ~~conductors are composed of~~ sintered ~~bodies~~ body of the electrically conductive paste according to ~~any one of Claims 1 to 4~~ Claim 1.

6 (Currently amended). The multilayer ceramic substrate according to Claim 5, wherein the wiring ~~conductors include~~ conductor is via hole conductor ~~conductors~~ disposed penetrating ~~specific layers~~ at least one of the ceramic layers.

7 (New). The electrically conductive paste according to Claim 1, wherein metal powder has an average particle diameter of 0.5 to 10 μm.

8 (New). The electrically conductive paste according to Claim 1, wherein the inorganic component is an oxide of at least one of Al, Si, Zr, Ni, Ti, Nb, Mn and Mg.

9 (New). The electrically conductive paste according to Claim 1, wherein the inorganic component is alumina or zirconia.

10 (New). The electrically conductive paste according to Claim 2, wherein the glass frit has a viscosity within the range of 800°C to 950°C. which satisfies $\log(\eta/Pa \cdot s) = 4$.

11(New). The electrically conductive paste according to Claim 10, wherein the content of the inorganic component is 0.5 to 8 percent by weight relative to the total weight of the metal powder and the inorganic component.

12 (New). The electrically conductive paste according to Claim 11, wherein metal powder has an average particle diameter of 0.5 to 10 μm.

13 (New). The electrically conductive paste according to Claim 12, wherein the inorganic component is an oxide of at least one of Al, Si, Zr, Ni, Ti, Nb, Mn and Mg.

14 (New). The electrically conductive paste according to Claim 12, wherein the inorganic component is alumina or zirconia.

15 (New). A multilayer ceramic substrate comprising a plurality of laminated ceramic layers and at least one wiring conductor disposed in association with the ceramic layers, wherein the wiring conductor is a sintered body of the electrically conductive paste according to Claim 4.

16 (New). The multilayer ceramic substrate according to Claim 15, wherein the wiring conductor is via hole conductor disposed penetrating at least one of the ceramic layers.

17 (New). A multilayer ceramic substrate comprising a plurality of laminated ceramic layers and at least one wiring conductor disposed in association with the ceramic layers, wherein the wiring conductor is a sintered body of the electrically conductive paste according to Claim 11.

18 (New). The multilayer ceramic substrate according to Claim 17, wherein the wiring conductor is via hole conductor disposed penetrating at least one of the ceramic layers.

19 (New). A multilayer ceramic substrate comprising a plurality of laminated ceramic layers and at least one wiring conductor disposed in association with the ceramic layers, wherein the wiring conductor is a sintered body of the electrically conductive paste according to Claim 13.

20 (New). The multilayer ceramic substrate according to Claim 19, wherein the wiring conductor is via hole conductor disposed penetrating at least one of the ceramic layers.